

JP05102343 A

MOUNTING STRUCTURE OF SEMICONDUCTOR DEVICE AND MOUNTING
METHOD OF SEMICONDUCTOR DEVICE

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Abstract:

PURPOSE: To provide a method by which the reliability on the connection is high and which never causes electric conductivity trouble, in case of mounting a semiconductor element on a glass board, with the active face opposite to it. **CONSTITUTION:** A semiconductor element 1 is loaded on a wiring board 4 where a through hole 9 is opened, and the adhesive for fixing is hardened by heat. Moreover, in case of having used a photosetting adhesive, it can be made the hardening from the rear of the semiconductor device and the hardening from the rear of the glass board. This way, by having opened a through hole, the adhesive can be escaped to outside, so it does not give stress to the connection. Moreover, even if trouble should be found, the semiconductor device could be removed simply from the glass wiring board.

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Application No. 03260072 JP03260072 JP, Filed 19911008, A1
Published 19930423

Original IPC(1-7): H01L02315
H05K01304

Patents Citing This One (3): US6274389 B1 20010814
Loctite (R&D) Ltd.

Mounting structure and mounting process from semiconductor
devices

US6316528 B1 20011113 Loctite (R&D) Limited
Thermosetting resin compositions